

Soarch



Product Change Notification - JAON-31FWIA899 (Convert To PDF)

Date:

26 Apr 2018

Product Category:

Memory

Affected CPNs:



Notification subject:

CCB 2730 and 2730.001 Final Notice: Qualification of HR-9004 die attach material for selected products available in 48L WFBGA (4x6x0.8mm) and 34L WFBGA (4x6x0.8mm) packages at LPI assembly site.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of HR-9004 die attach material for selected products available in 48L WFBGA (4x6x0.8mm) and 34L WFBGA (4x6x0.8mm) packages at LPI assembly site.

Pre Change:

Using EM-700J die attach material.

Post Change:

Using HR-9004 die attach material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	LPI assembly site	LPI assembly site
Wire material	Au wire	Au wire
Die attach material	EM-700J	HR-9004
Molding compound material	G770HT	G770HT
Substrate material	BT Substrate	BT Substrate

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To Improve on-timed performance by qualifying HR-9004 die attach material. The EM-700J die attach material will no longer be available for use to assemble selected products available in 48L WFBGA (4x6x0.8mm) and 34L WFBGA (4x6x0.8mm) packages at LPI assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

May 26, 2018 (date code: 1821)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

		September 2016			->	April 2018			May 2018						
Workweek	35	36	37	38	39		14	15	16	17	18	19	20	21	22
Initial PCN Issue Date		X													
Qual Report Availability										X					
Final PCN Issue Date										X					
Estimated														Χ	



Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

September 09, 2016: Issued initial notification.

April 26, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on May 26, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-31FWIA899_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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